

ABSTRACT OF THE DISCLOSURE

An electronic component having an electrode structure to increase an allowance positional deviation in a mounting process as well as a method and a structure for mounting a semiconductor device are provided. The semiconductor device includes, on electrodes, connection materials connecting the semiconductor device and a substrate. The connection materials include a composite connection material formed of a core and a conductor covering the core, the core having an a low modulus of elasticity at room temperature smaller than that of the conductor at room temperature, and a single-layer connection material formed of a conductor.

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